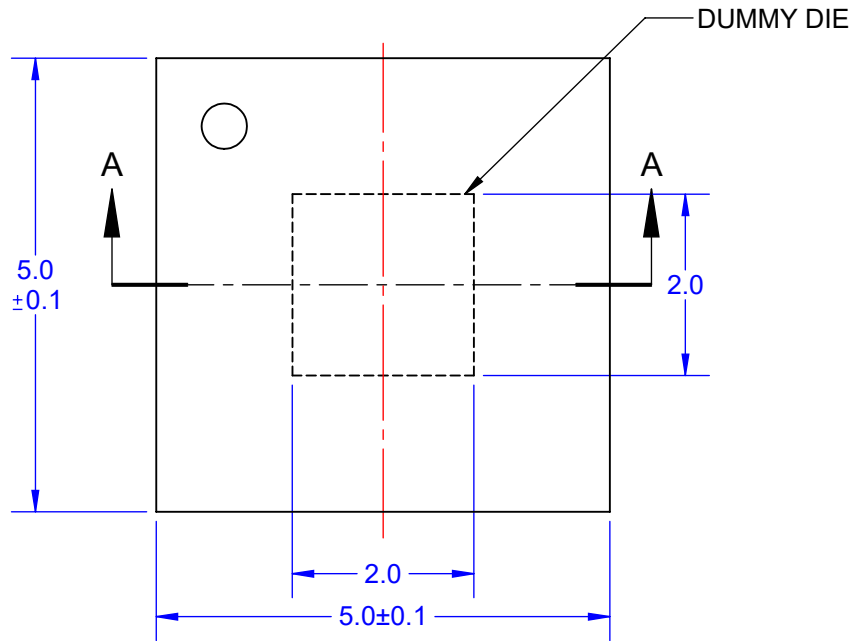
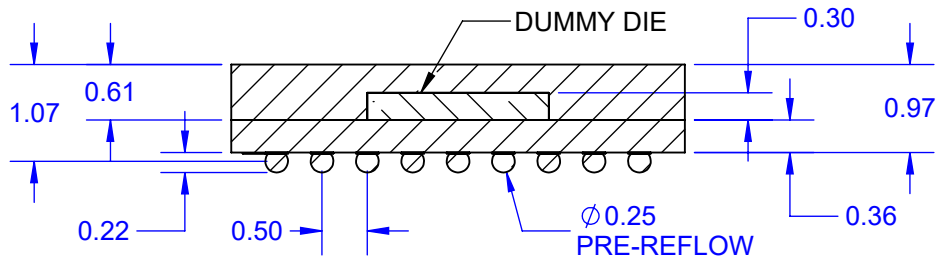
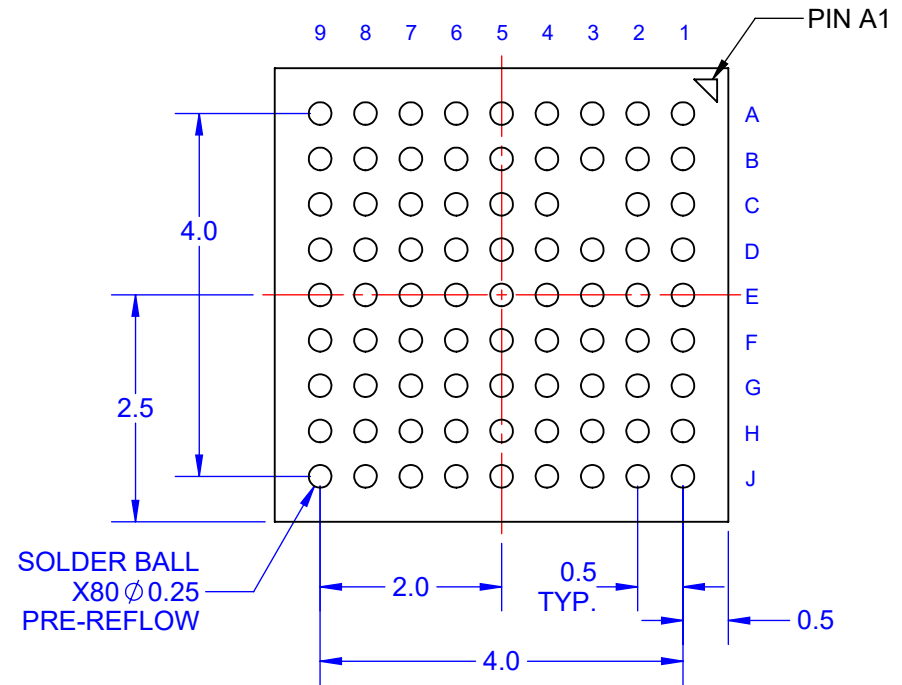


## TOP VIEW



## BALL VIEW




SECTION A-A  
SCALE 12 : 1

Notes: (Unless Otherwise Specified).

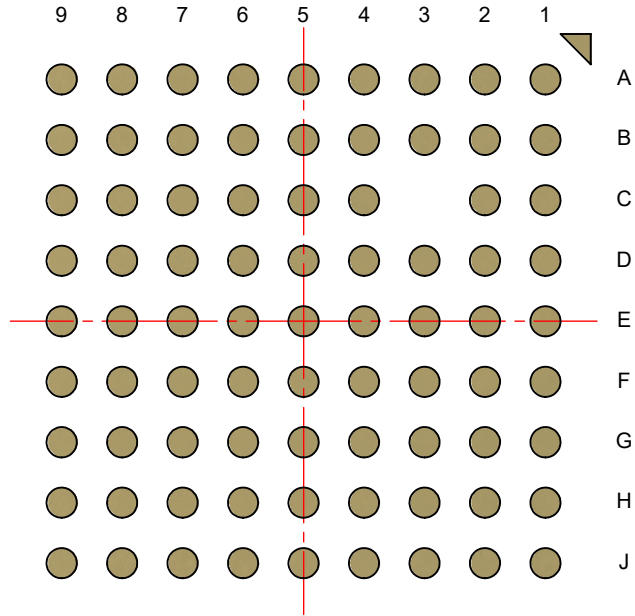
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.25mm (10 MIL).
- 5) PAD Cu DIAMETER: 0.355mm (14 MIL).
- 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN ATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

### PART NUMBER TABLE

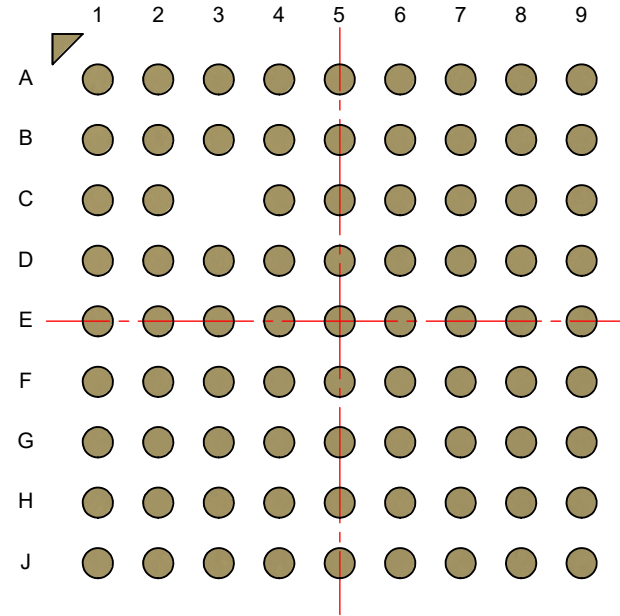
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE
BGA80T.5C-9x9-D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	YES
BGA80T.5-9x9-D	Sn63/Pb37	Sn63	NO	YES

APPROVALS	DATE				
DRAWN T. Au	7/15/2021				
ENG M. Hart	7/15/2021	TITLE		BGA80T.5C-9x9-D DUMMY BGA	
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		15:1	A	165549	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

### BALL VIEW



### BOTTOM SIDE (TOP X-RAY VIEW)



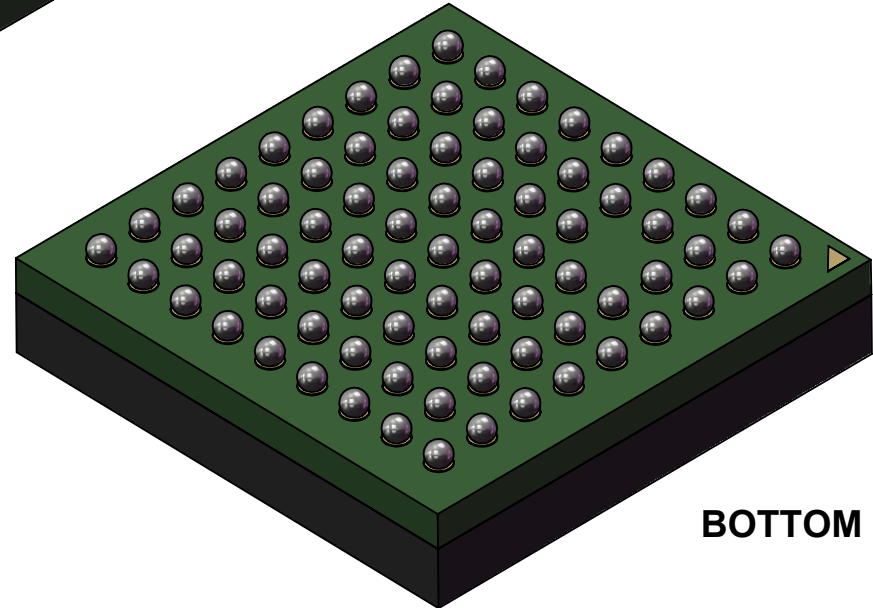
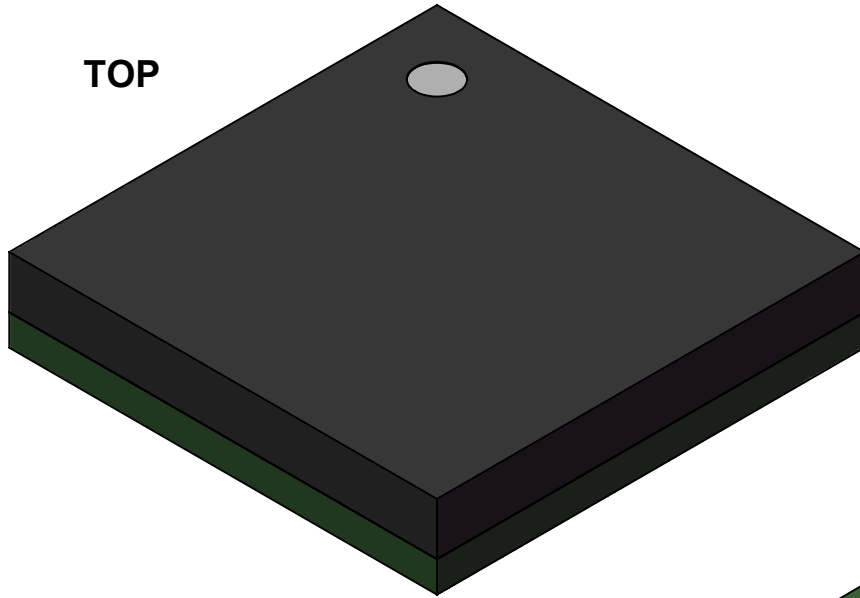
**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.  
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.335mm (14 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.25mm (10 MIL).

<b>TopLine<sup>®</sup></b>			
TITLE		BGA80T.5C-9x9-D DUMMY BGA	
SCALE	SIZE	DRAWING NO.	REV
16:1	A	165549	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

# MODEL

TOP



BOTTOM

**TopLine**<sup>®</sup>

TITLE BGA80T.5C-9x9-D  
DUMMY BGA

SCALE 8:1	SIZE A	DRAWING NO. 165549	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3